

## Definitions

### **homogeneous material**

Toshiba Semiconductor Company defines “homogeneous material” to mean a material that cannot be mechanically disjointed into different materials. The term “homogeneous” is understood as “of uniform composition throughout” so examples of “homogeneous materials” would be individual types of plastics, ceramics, glass, metals, alloys, paper, board, resins and coatings. Toshiba Semiconductor Company defines the term “mechanically disjointed” means that the materials can be, in principle, separated by mechanical actions such as unscrewing, cutting, crushing, grinding and abrasive processes.

### **Contain, Containing, and Contained**

“Contain”, “Containing”, and “Contained” as the case may be, refers to intentional use of a substance in the “Parts,” and “Materials,” of a product in order to obtain an intended performance or function. Should such a substance remain in or attached to “Products,” “Parts,” or “Materials,” as a result of the manufacturing process, in a quantity that unintentionally exceeds the maximum concentration value designated by Toshiba, the substance is also judged to be “Contained”. However, the residuum after a chemical reaction (such as monomer) and dopants in semiconductor chip, etc., are excluded.

### **RoHS Compatible**

Toshiba Semiconductor Company defines “RoHS Compatible” semiconductor products as products that either (i) Contain no more than a maximum concentration value of 0.1% by weight in homogeneous materials for lead, mercury, hexavalent chromium, polybrominated biphenyls (PBBs) and polybrominated diphenyl ethers (PBDEs) and of 0.01% by weight in homogeneous materials for cadmium; or (ii) fall within any of the stated exemptions set forth in the Annex to the RoHS Directive. Also, Toshiba Semiconductor Company defines RoHS Compatibility as a product being RoHS Compatible.

### **RoHS Directive**

Toshiba Semiconductor Company defines the “RoHS Directive” as the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

## **Lead(Pb)-Free**

Toshiba Semiconductor Company defines capitalized “Lead(Pb)-Free” products as those Containing no more than 0.1 percent lead(Pb) by weight in homogeneous materials. This does not mean that Toshiba Semiconductor products labeled "Lead(Pb)-Free" are entirely free of lead(Pb).

## **Lead(Pb)-Free Finish**

In addition to Lead(Pb)-Free (products with no more than 0.1 percent lead(Pb) by weight in homogeneous materials), Toshiba Semiconductor Company will offer products that have Lead(Pb)-Free terminals, which will be referred to as “Lead(Pb)-Free Finish.” The Lead(Pb)-Free Finish products may Contain greater than 0.1 percent lead(Pb) by weight in homogeneous materials in portions of the product other than the terminals (based on the exemption(s) in the RoHS Directive), for example, in internal solder used to connect the semiconductor silicon to the package. This does not mean that Toshiba Semiconductor products that are labeled "Lead(Pb)-Free Finish" have terminals that are entirely free of lead(Pb).

## **[[G]]/RoHS COMPATIBLE**

“[[G]]/RoHS COMPATIBLE” will be labeled on the packages of the products determined as RoHS Compatible by Toshiba Semiconductor Company and not falling within any of the stated exemptions set forth in the Annex to the RoHS Directive. This does not mean that Toshiba Semiconductor Company products labeled “[[G]]/RoHS COMPATIBLE “ are entirely free of controlled substances of the RoHS Directive and does not constitute a warranty that such products will comply with the specific laws and/or regulations adopted in any particular jurisdiction.

## **[[G]]/RoHS [[Pb]]**

“[[G]]/RoHS [[Pb]]” will be labeled on the packages of the products that Toshiba Semiconductor Company has determined to be RoHS Compatible based on the exemption(s) in the RoHS Directive and reflect the substance that exceeds the maximum concentration value as designated by Toshiba Semiconductor Company to determine if specific products are RoHS Compatible in such products. [[G]]/RoHS [[Pb]] is the notation where Lead(Pb) is Contained more than the maximum concentration value as designated as one of the application which fall into such exemption(s) by Toshiba Semiconductor Company in the RoHS Compatible product based on such exemption(s). This does not mean that Toshiba Semiconductor Company products labeled “[[G]]/RoHS [[Pb]] “ are entirely free of controlled substances under the RoHS Directive and does not constitute a warranty that such products will comply with the specific laws and/or regulations adopted in any particular jurisdiction.

## **[[Pb]]/INCLUDES > MCV**

“[[Pb]]/INCLUDES > MCV” will be labeled on the packages of the products that Toshiba Semiconductor Company has determined NOT to be RoHS Compatible and reflect the substance that exceeds the maximum concentration value as specified by Toshiba Semiconductor Company to determine if specific products are RoHS Compatible in such products. MCV means the maximum concentration value. [[Pb]]/INCLUDES > MCV is the notation where Lead(Pb) is Contained more than the maximum concentration value as designated by Toshiba Semiconductor Company in the product which is not RoHS Compatible.

## **Legal Note.**

These definitions are not intended to interpret the RoHS Directive or any other applicable law or regulation (collectively the “Laws”) and do not constitute legal advice. The Laws should always be read and understood (as they constitute the law), in contrast with the information contained herein, which is intended to be informative but has no legal authority. You should refer to the Laws for a full statement of the legal requirements and in the case of any doubt take independent advice, including your own legal advice. The Laws may be revised from time to time, so users should take care to keep themselves informed.